Am₂₆LS₃₈

Quad Differential Backplane Transceiver



DISTINCTIVE CHARACTERISTICS

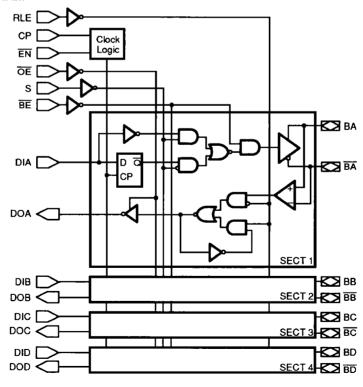
- 10 Mb data rate
- 0.45 V DC noise margin
- Blasing line terminations allow low voltage swing while maintaining high noise margin
- Pair delay 55 ns maximum
- Controlled driver skew to minimize noise
- Driver register and receiver latch with register bypass mode
- Driver output short-circuit protected to Vcc limits
- Outputs disabled during power-up and down
- Three-state receiver outputs maintain Hi-Z during power-up and down and over Vcc range

GENERAL DESCRIPTION

The Am26LS38 is a high performance backplane transceiver designed to integrate Schottky TTL performance, high noise immunity and wired logic capability into a low cost differential backplane structure. The resulting

backplane can have up to 24 receiver unit loads in a party-line, wired-OR logic configuration, with a guaranteed fail-safe state, and operates from a single 5 V power supply.

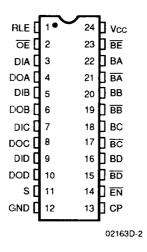
BLOCK DIAGRAM



02163D-1

CONNECTION DIAGRAM Top View

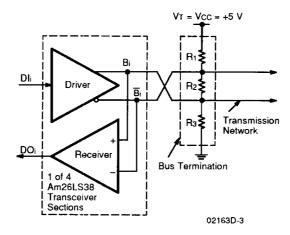
DIP



Note:

Pin 1 is marked for orientation.

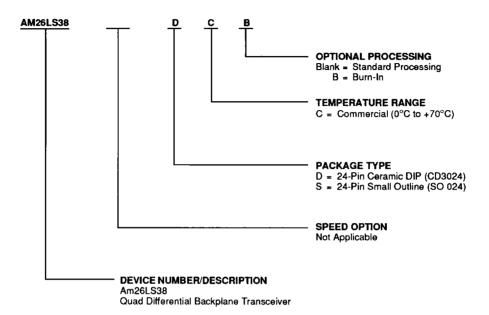
SYSTEM CONFIGURATION DIAGRAM



ORDERING INFORMATION

Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:



Valid Combinations					
AM26LS38	DC, DCB, SC				

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.



PIN DESCRIPTION

Pin No.	Name	1/0	Description
22, 20 18, 16, 21, 19, 17, 15	BA, BB, BC, BD (Bi), BA, BB, BC, BD (Bi)	1/0	Paired open emitter (Bi)/ open collector (Bi) driver outputs and receiver inputs. The driver outputs are either simultaneously active or simultaneously inactive. In the inactive state (Dli = LOW) both drivers (Bi and Bi) are turned off and the voltage differential representing the OFF state is determined by the line terminating resistor networks. In the active state (Dli = HIGH), both drivers are driven on and act to reverse the voltage differential across the line to produce the ON state. The open-emitter/open-collector outputs are always connected in a wried-OR (or wired-AND) configuration. A driver is disabled by making its outputs inactive.
23	BE	-	Bus Enable operates to enable or disable all output drivers by making them inactive when \overline{BE} = HIGH and controlled by data input when \overline{BE} = LOW.
13	СР	1	Clock Pulse input to the driver register enters data on the LOW-to-HIGH transition.
3, 5, 7, 9	DIA, DIB, DIC, DID (DIi)	i	Data inputs each driver's buffer or register. A HIGH input to DI will result in an active (ON) output. A LOW input will cause an inactive (OFF) output.
4, 6, 8, 10	DOA, DOB, DOC, DOD (DOi)	0	Receiver data latch outputs. An inactive bus (OFF state) will produce a LOW DOi output and an active bus (ON state) will produce a HIGH DOi output.
14	ĒN	1	Clock Enable for the driver registers. EN = LOW enables DI data to be clocked into the respective register. EN = HIGH acts to hold previous data in each register regardless of the state of CP.
2	ŌĒ	1	Output Enable for the receiver latch output buffer. When \overline{OE} is LOW the outputs are enabled. When \overline{OE} is HIGH all receiver outputs are in the high impedance state.
1	RLE	Ī	Receiver Latch Enable for the receiver latches. When RLE is HIGH the latches are transparent. When RLE is LOW received data meeting the setup and hold requirements relative to the HIGH-to-LOW transition of RLE will be stored.
11	S	1	Select input control for the drivers. When S is HIGH driver data from the registers will be selected (Register Mode). When S is LOW (Buffer Mode) the drivers respond to the DI _i inputs directly, bypassing the driver registers.

				Inputs	3				(Output	s	
RLE	СР	EN	ŌĒ	S	BE	Dli	Bi	Bı	Bi	Bi	DOi	Function
H	X X	X X	L	L	نـ نـ	L	NA NA	NA NA	H	H	L H	Driver buffer mode (loop test)
H	↑	L	L	H H	ال ال	H	NA NA	NA NA	L	H	L H	Driver register mode
H	X X	X	L	X X	ı ı	×	L H	H	NA NA	NA NA	L H	Receiver latch mode
L	Х	Х	L	Х	π_	х	Х	х	х	×	DOin-1	Receiver in circulation
X	×	Х	Н	X	Н	×	х	Х	х	Х	Z	Receiver output in high impedance state

H = HIGH

L = LOW

↑ = LOW-to-HIGH transition of clock

DOin-1 = Previous state of DO

Z = High impedance

X = Don't care

NA = Not applicable

FUNCTIONAL DESCRIPTION

The Am26LS38 represents a new approach in backplane transceiver design. Its unipolar differential signaling scheme minimizes problems associated with crosstalk and the loss of noise immunity due to common mode voltage while providing high speed, party line and wired logic capabilities.

A good ground system and shielding are the best methods for limiting noise on the backplane. Ground planes can significantly reduce inductive ground voltage ringing. Where multilayer PC backplane are not a reasonable choice, a differential bus can be created using the Am26LS38 and twisted pair or any balanced transmission medium.

A backplane designed with an Am26LS38 has 3 main elements; 1) a driver section, 2) a receiver section, 3) and a controlled impedance differential line with a prebiasing line termination. The scheme for driver, receiver, and termination resistors is shown in Figure A.

System Operation

The system has two operational states.

- 1. Active driver outputs on
- 2. Passive driver outputs off

This 2-state (active/passive) operation makes passive or wired logic functions possible. In the passive state, the lines assume a known polarity and voltage (pre-biased bus). The passive bus state may be assigned either the false (wired-OR) or true (wired-AND) sense, potentially reducing the number of backplane signal lines.

The 2-state driver employs active pull-down (open collector) and active pull-up (open emitter) output stages (Figure A). When a driver is active, both output stages turn on. This impresses a 0.5 V minimum voltage differential on the bus, reversing the voltage across $R_{\rm 2}$. In the passive mode both output stages are off. The voltage levels and polarities return to the conditions set by the pre-biasing resistive network. In either state the voltage across the differential lines are symmetrical about Vcc/2. The system achieves high speeds because the voltage levels required to change state are very close together.

The receiver is designed with a ±50 mV threshold voltage. This low threshold level combined with a driver output greater than 500 mV provides a high degree of tolerance to attenuation and reflection effects in the cable. Receiver hysteresis provides differential noise immunity. Without hysteresis, a small amount of noise around the switching threshold could cause errors.

Propagation delay skew (tphL – tpLH) is controlled. The system allows up to 1.5 V of common mode voltage.

Terminating the Transmission Line or Bus

Common mode reflections in the line can be reduced significantly by symmetrically terminating the bus. This increases the tolerance to common mode noise. Centering the network at Vcc/2 ($R_1 = R_3$) further improves the performance by causing all induced noise and reflections to appear as a common mode signal (Figure B).

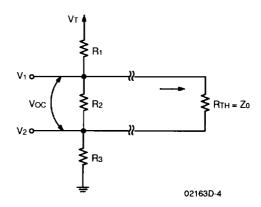
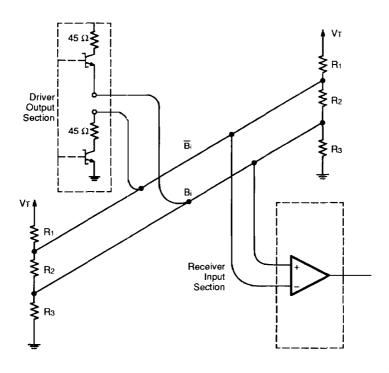


Figure B. Termination Circuit



02163D-5

Figure A. The Scheme for Driver, Receiver, and Termination Resistors

A first order approximation of resistor values may be developed by letting the ratio of R_1 to R_2 be 2:1, and the Thevenin equivalent resistance of the termination equal the characteristic impedance of the line (Z_0) .

Then:

(1)
$$V_{OC} = V_T \frac{R_2}{R_2 + 2R_1}$$

(2)
$$R_{TH} = \frac{2R_1R_2}{2R_1 + R_2}$$

From equation (1) and (2),

$$(3) R_1 = \frac{V_T R_{TH}}{2V_{OC}}$$

(4)
$$R_2 = \frac{V_T R_{TH}}{V_T - V_{OC}}$$

If V_T = 5 V, V_{CC} = 1.0 V, and R_{TH} = 90 Ω = Z₀, we can derive that R₁ ~220 Ω , R₂ ~110 Ω .

Second order adjustments require attention to unit loading factors (receiver differential input resistance is in parallel with R_2), transmission rates and a host of other factors.

Data Path

Figure C shows the data path from one driver to another receiver for one bit of the bus interface.

The transmit register or buffer and receiver latch are configured to provide two modes of operation. The register and latch can provide local storage for output and input data. In the non-storage mode the buffer input to the driver can be selected and the receiver can be wired transparent. Incorporating storage on-chip provides improved speed and lower package count without significant penalty in the non-storage mode.

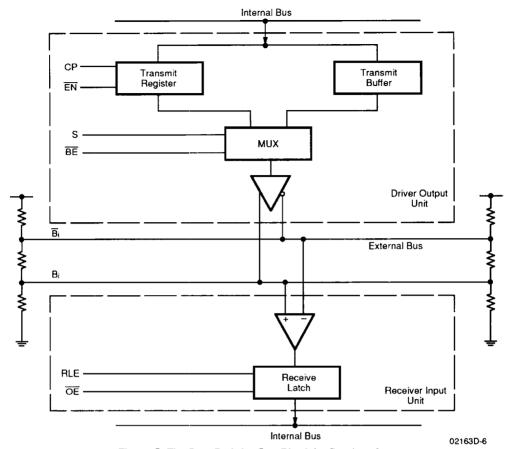
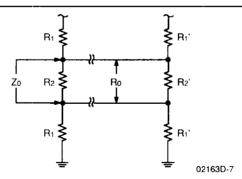


Figure C. The Data Path for One Bit of the Bus Interface



Equivalent Circuit Recommended Termination

Termination Resistors and Equivalent Impedance

Zo	R ₁ = R ₁ '	$R_2 = R_2$
90 Ω	220 Ω	110 Ω
120 Ω	300 Ω	150 Ω

Minimum line V₀ (differential voltage) = 0.5 V

Equivalent Termination Versus DC Resistance

Zo	Ro
88.0 Ω	44.0 Ω
120.0 Ω	60.0 Ω



ABSOLUTE MAXIMUM RATINGS

Supply Voltage	7.0 V
Common Mode Range 0 to	Vcc
Differential Mode Range (REC) 0 to	Vcc
Logic Inputs	5.5 V
Storage Temperature Range65°C to +1	50°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Temperature	. 0°C to +70°C
Supply Voltage+4.	75 V to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

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DC CHARACTERISTICS over operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур.	Max	Unit	
Bus Driver	Output	•	_				
Vo	Output Differential Voltage (Driver Active) V _{Bi} — V _{Bi}	BE = LOW Di = HIGH Test Circuit #1		0.5			٧
Iss	Output Current	DI = HIGH Ia		-22.5	-55	-115	mA
		Test Circuit #2 BE = LOW	lb	+22.5	+55	+115	mA
Isc	Output Short Circuit Current	Vcc = 5.5 V		-75	-150	-250	mA
Bus Receive	er Input	•			•		
Vтн	Differential Input Threshold Voltage	VCM = 0 to VCC VOUT = VOL or VOL	1	-50	±10	+50	mV
Rin	Input Resistance to GND	0 ≤ Vcc ≤ Vcc Ma	x	4	5.7		kΩ
Rin	Differential Input Resistance	0 ≤ Vcc ≤ Vcc Ma	x	8	11.4		kΩ
Vos	Center Voltage	Test Circuit #3 Active and Passive		2.0	Vcc/2	3.0	V
Vos - Vos	Center Voltage Difference (Active vs. Passive)	Test Circuit #3			90	300	mV
Non-Bus Inj	out and Outputs						
Vон	Output HIGH Voltage	$\Delta V_{IN} = +0.1 \text{ V}$	I _{OH} = -15 mA	2.4	3.4		٧
			I _{OH} = -24 mA	2.0	3.3		>
Vol	Output LOW Voltage	$\Delta V_{IN} = -0.1 \text{ V}$	MIL, I _{OL} = 32 mA			0.5	٧
			COM'L, l _{OL} ≈ 48 mA			0.5	٧
ViH	Input HIGH Voltage	Guaranteed Input Voltage for All Inpu		2.0			v
VIL	Input LOW Voltage	Guaranteed Input Voltage for All Inpu	•			0.8	· V
l _{lL}	Input LOW Current	V _{IN} = 0.4 V	Data		-275	-400	μА
			Control		-0.65	-1.0	mA
			Clock		-0.65	-1.0	mA
lin	Input HIGH Current	ViN = 2.7 V			0.1	+50	μΑ
Isc	Output Short Circuit Current	Vcc = 5.5 V		-75	-150	-250	mA
lı .	Input Leakage Current	VIN = 5.5 V				1	mA
Vic	Input Clamp Voltage	lin = -18 mA			-0.75	-1.2	٧
loz	Leakage Current Passive	V ₀ = 2.4 V				+50	μА
		V ₀ = 0.4 V				-50	μА
lcc	Power Supply Current	BE, OE = HIGH				145	mA



SWITCHING CHARACTERISTICS (T_A = +25°C, V_{cc} = 5.0 V)

Parameter Symbol				ons	Min	Тур.	Max	Unit
toba	Dli to Bi/Bi Propagation Delay	Active	BE = LOW	Test Circuit #1		7	10	กร
tobe		Passive	S = LOW			7	10	ns
tcba	CP to Bi/B Propagation Delay	Active	BE = LOW	Test Circuit #1		10.5	16	ns
tcBP		Passive	S ≖ HIGH			13	16	ns
1PA	BE to Bi/Bi Propagation Delay	Active	DI _i = HIGH	Test Circuit #1		8.5	12	ns
tpp		Passive	S = LOW			4	8	ns
ts	Dli to Clock Setup Time		BE = LOW		5	2.5		ns
tH	Dli to Clock Hold Time				2	0		ns
ts	EN to Clock Setup Time			ĺ	8	4		ns
tH	EN to Clock Hold Time				0	-4		ns
ts	Bi/Bi to RLE Setup Time				5	2.5		ns
tH	Bi/Bi to RLE Hold Time				2	0.7		ns
tplz/tpHz	OE to DOi Disable Time		CL = 50 pF	Test Circuit #4			20	ns
tplz/tphz			CL = 5 pF	Test Circuit #4			13	ns
tpzL	OE to DOi Disable Time			Test Circuit #4			17	ns
tpzh]			ļ			17	ns
tplH	RLE to DOi		OE = LOW	Test Circuit #4		11	13	ns
tphL	1					14	17	ns
tprx	Bi/Bi to DOi		RLE = HIGH OE = LOW	Test Circuit #4	_	12	17	ns
tPLH	BE to DOi Propagation Delay		RLE = HIGH	Test Circuits		15	25	ns
tphL_			OE = LOW	#1, #4				
t PLH	Dli to DOi (Buffer Mode)		S = LOW	Test Circuits		18	25	ns
tphi.			RLE = HIGH	#1, #4				ı
<u> </u>			OE = LOW					
tplh	CP to DOi (Register Mode)		S = HIGH	Test Circuits		22	28	ns
tpHL			RLE = HIGH OE = LOW	#1, #4				
tpwL	Clock Pulse Width	LOW			10	3		ns
tpwH		HIGH			10	5		ns
1PWH	RLE Pulse Width	HIGH		-	10	6		ns
tskew	Propagation Delay Skew (tpLH - tpHL)		V _{CC} = 5 V C _L = 50 pF Measurement	Test Circuit #1		±1	±5	ns

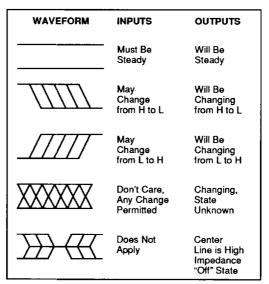
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SWITCHING CHARACTERISTICS over operating range unless otherwise specified

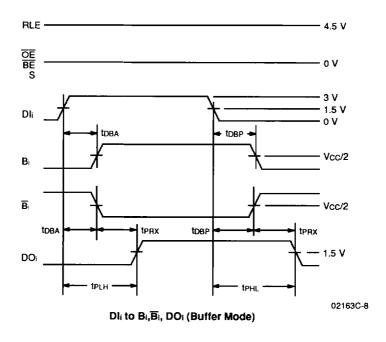
Darameter	Parameter				TA = 0 to Vcc = 5.0		
Symbol	Parameter Description		Test Conditions	8	Min	Max	Unit
tDBA	Dli to Bi/ Bi Propagation Delay	Active	BE = LOW	Test Circuit #1		12	ns
tobp		Passive	S = LOW			12	ns
tcba	CP to Bi/ Bi Propagation Delay	Active	BE = LOW	Test Circuit #1		20	ns
tcbp		Passive	S = HIGH			20	ns
tpa	BE to Bi/ Bi Propagation Delay	Active	Dli = HIGH	Test Circuit #1		17	กร
tpp	1	Passive	S = LOW			12	ns
ts	Dli to Clock Setup Time		BE = LOW		7		ns
tн	Dli to Clock Hold Time]		3		ns
ts	EN to Clock Setup Time]		10		ns
tн	EN to Clock Hold Time]		0		ns
ts	Bi/ Bi to RLE Setup Time]		7		ns
tн	Bi/ Bi to RLE Hold Time		<u></u>		3		ns
tplz/tpHz	OE to DO _i Disable Time		C _L = 50 pF	Test Circuit #4		17	ns
tplz/tpHz			C _L = 5 pF	Test Circuit #4		10	ns
tpzl	OE to DO _i Enable Time		Test Circuit #4			15	ns
tpzh						15	ns
tplH	RLE to DO _i		OE = LOW	Test Circuit #4		15	ns
tphl.						20	ns
tprx	B/B _i to DO _i		RLE = HIGH OE = LOW	Test Circuit #4		21	ns
tplH	BE to DO _i Propagation Delay		RLE = HIGH	Test Circuits		32	ns
tphl			OE = LOW	#1, #4			
tplH	Dl _i to DO _i (Buffer Mode)		S = LOW	Test Circuits			
t _{PHL}			RLE = HIGH OE = LOW	#1, #4		30	ns
t PLH	CP to DO _i (Register Mode)		S = HIGH	Test Circuits		35	ns
t _{PHL}			RLE = HIGH OE = LOW	#1, #4			
tpwL	Clock Pulse Width	LOW			10		ns
tрwн		HIGH	1		10		กร
tewn	RLE Pulse Width	HIGH			13		ns
tskew	Propagation Delay Skew (tplh - tphl)		Vcc = 5 V CL = 50 pF Measurement Vo	Test Circuit #1		±7	ns

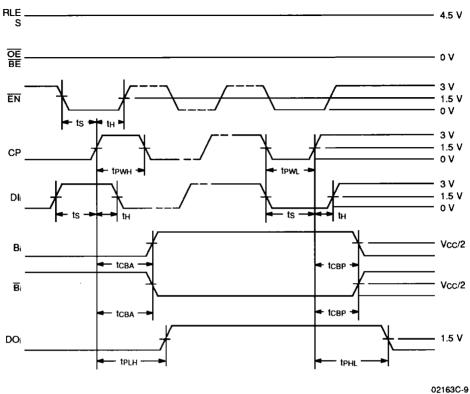


KEY TO SWITCHING WAVEFORMS

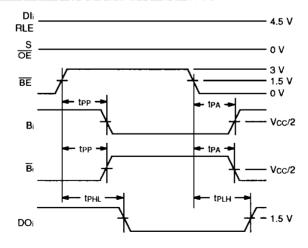


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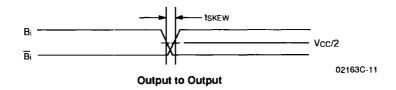


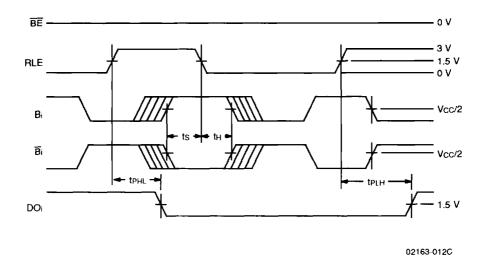
CP to B_i,B̄_i, DO_i (Register Mode)



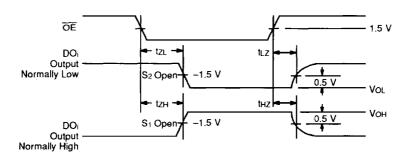
BE to Bi, Bi, DOi (Passive and Active)

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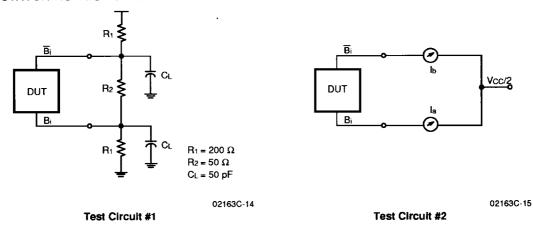
RLE to DOi



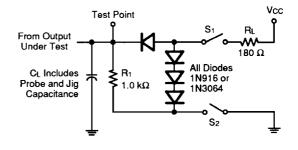
OE to DO

02163-013C

SWITCHING TEST CIRCUITS



DUT 10 Ω Vos



02163C-16

Test Circuit #3

Test Circuit #4

Notes:

- 1. C_L = 50 pF unless otherwise specified.
- 2. S₁ and S₂ are closed except where shown.

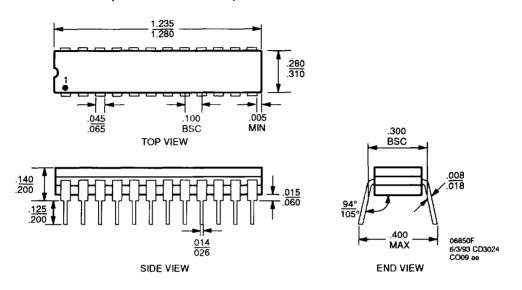
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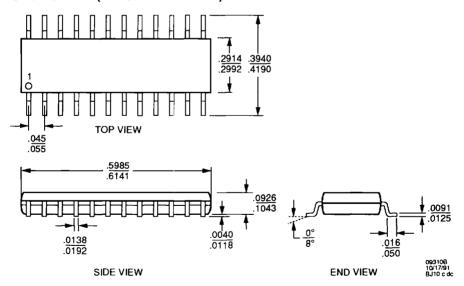
PHYSICAL DIMENSIONS*

CD3024

24-Pin Ceramic DIP (measured in inches)



SO 024 24-Pin Small Outline (measured in inches)



*For reference only. BSC is an ANSI standard for Basic Space Centering.

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